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Chemical Substances in Lattice Semiconductor Products

Recent trends in the semiconductor industry are driving toward more environmentally friendly materials. These changes are due to enhanced environmental awareness, and legislative restrictions of hazardous materials, such as the European Parliament’s Directive 2002/95/EC on Restriction of Hazardous Substances (RoHS), China’s Measures for the Administration of the Control of Pollution by Electronic Information Products and others. Lattice Semiconductor is fully committed to providing environmentally friendly processes, products, and shipping packages that meet our customers’ needs and meet our corporate commitment to protect the natural environment. Lattice has been actively tracking and is fully supportive of the various industry efforts throughout the world to phase out the use of lead (Pb) and other undesirable elements from electronic equipment materials and manufacturing processes.

Lattice currently offers the broadest line of Pb-Free products in the PLD marketplace. We have worked closely with our manufacturing partners to identify and rapidly eliminate the following list of substances from our Pb-free products. As a result, these products are now RoHS compliant. Lattice Semiconductor Corporation represents that all Lattice Pb-free plastic parts, including Lattice's original packaging materials, do not contain the chemical substances listed below:

- 1. Lead (Pb)*
- 2. Cadmium (Cd)
- 3. Mercury (Hg)
- 4. Hexavalent chromium (CrVI)
- 5. Polybrominated Biphenyl (PBB)
- 6. Polybrominated Diphenyl Ethers (PBDE)

* Pb may be contained in the die-to-package interconnect (die bumping) in flip-chip packages, under EU RoHS “flip chip” exemption #15 (2005/747/EC).

Lattice Semiconductor Corporation further represents that its plastic parts that are **not** designated as Pb-free do not contain items 2 through 6 above (often referred to as “RoHS 5/6 compliant”), but may contain the following substance in the indicated concentration:

<u>Substance</u>	<u>Concentration/Location</u>
Lead (Pb)	Nominal 15%Pb lead plating
	Nominal 37%Pb BGA solder ball
	Nominal 37-95%Pb flip-chip solder bump

Be assured that your business is valued greatly by Lattice Semiconductor and that we will do everything within our power to provide you with the highest level of service and support and with the broadest portfolio of high performance Field Programmable Gate Arrays (FPGAs), Field Programmable System Chips (FPSCs) and high-performance ISP™ programmable logic devices (PLDs).

Regards,

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